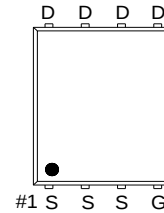
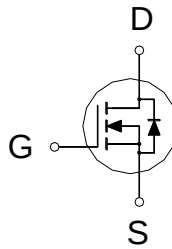




PRODUCT SUMMARY

$V_{(BR)DSS}$	$R_{DS(ON)}$	I_D
150V	9.3m Ω	83A



G. GATE
D. DRAIN
S. SOURCE

ABSOLUTE MAXIMUM RATINGS ($T_A = 25\text{ }^{\circ}\text{C}$ Unless Otherwise Noted)

PARAMETERS/TEST CONDITIONS		SYMBOL	LIMITS	UNITS
Drain-Source Voltage		V_{DS}	150	V
Gate-Source Voltage		V_{GS}	± 20	V
Continuous Drain Current	$T_C = 25\text{ }^{\circ}\text{C}$	I_D	83	A
	$T_C = 100\text{ }^{\circ}\text{C}$		58	
Pulsed Drain Current ¹		I_{DM}	208	
Continuous Drain Current	$T_A = 25\text{ }^{\circ}\text{C}$	I_D	15	
	$T_A = 70\text{ }^{\circ}\text{C}$		13	
Continuous Drain Current ⁴	$T_A = 70\text{ }^{\circ}\text{C}$		11.8	
Avalanche Current		I_{AS}	18	
Avalanche Energy	$L = 1\text{mH}$	E_{AS}	162	mJ
Power Dissipation	$T_C = 25\text{ }^{\circ}\text{C}$	P_D	150	W
	$T_C = 100\text{ }^{\circ}\text{C}$		75	
Power Dissipation ³	$T_A = 25\text{ }^{\circ}\text{C}$	P_D	5.1	W
	$T_A = 70\text{ }^{\circ}\text{C}$		3.6	
Operating Junction & Storage Temperature Range		T_j, T_{stg}	-55 to 175	$^{\circ}\text{C}$

THERMAL RESISTANCE RATINGS

THERMAL RESISTANCE		SYMBOL	TYPICAL	MAXIMUM	UNITS
Junction-to-Ambient ²	$t \leq 10\text{s}$	$R_{\theta JA}$		29	$^{\circ}\text{C} / \text{W}$
Junction-to-Ambient ²	Steady-State	$R_{\theta JA}$		58	
Junction-to-Case	Steady-State	$R_{\theta JC}$		1	

¹Pulse width limited by maximum junction temperature.

²The value of $R_{\theta JA}$ is measured with the device mounted on 1in² FR-4 board with 2oz. Copper, in a still air environment with $T_A = 25^{\circ}\text{C}$.

³The Power dissipation is based on $R_{\theta JA}$ $t \leq 10\text{s}$ value.

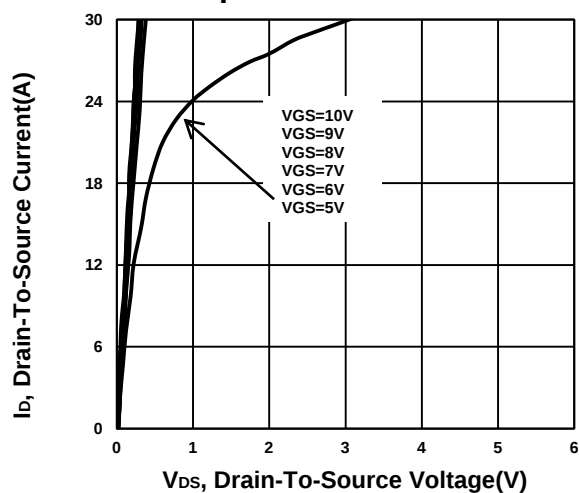
⁴ $R_{ds(on)}$ Conditions is $V_{GS} = 7\text{V}$.

ELECTRICAL CHARACTERISTICS ($T_J = 25^\circ\text{C}$, Unless Otherwise Noted)

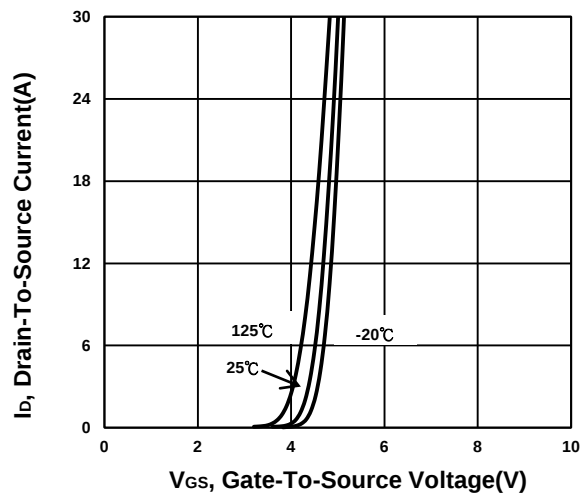
PARAMETER	SYMBOL	TEST CONDITIONS	LIMITS			UNITS
			MIN	TYP	MAX	
STATIC						
Drain-Source Breakdown Voltage	$V_{(BR)DSS}$	$V_{GS} = 0V, I_D = 250\mu A$	150			V
Gate Threshold Voltage	$V_{GS(th)}$	$V_{DS} = V_{GS}, I_D = 250\mu A$	2	3.3	4	
Gate-Body Leakage	I_{GSS}	$V_{DS} = 0V, V_{GS} = \pm 20V$			± 100	nA
Zero Gate Voltage Drain Current	I_{DSS}	$V_{DS} = 150V, V_{GS} = 0V$			1	μA
		$V_{DS} = 150V, V_{GS} = 0V, T_J = 125^\circ C$			100	
Drain-Source On-State Resistance ⁵	$R_{DS(ON)}$	$V_{GS} = 10V, I_D = 20A$		7.9	9.3	$m\Omega$
		$V_{GS} = 7V, I_D = 10A$		8.8	11	$m\Omega$
Forward Transconductance ⁵	g_{fs}	$V_{DS} = 5V, I_D = 20A$		22		S
DYNAMIC						
Input Capacitance	C_{iss}	$V_{GS} = 0V, V_{DS} = 75V, f = 1MHz$		3497		pF
Output Capacitance	C_{oss}			304		
Reverse Transfer Capacitance	C_{rss}			7		
Gate Resistance	R_g	$V_{GS} = 0V, V_{DS} = 0V, f = 1MHz$		1.3		Ω
Total Gate Charge ⁶	Q_g	$V_{GS} = 10V, V_{DS} = 75V, I_D = 20A$		46		nC
Gate-Source Charge ⁶	Q_{gs}			16		
Gate-Drain Charge ⁶	Q_{gd}			13		
Turn-On Delay Time ⁶	$t_{d(on)}$	$V_{DD} = 75V,$ $I_D \cong 20A, V_{GS} = 10V, R_{GEN} = 6\Omega$		27		nS
Rise Time ⁶	t_r			71		
Turn-Off Delay Time ⁶	$t_{d(off)}$			40		
Fall Time ⁶	t_f			73		
SOURCE-DRAIN DIODE RATINGS AND CHARACTERISTICS ($T_J = 25^\circ C$)						
Continuous Current	I_S				83	A
Forward Voltage ⁵	V_{SD}	$I_F = 20A, V_{GS} = 0V$			1.2	V
Reverse Recovery Time	t_{rr}	$I_F = 20A, di_F/dt = 100A/\mu s$		94		nS
Reverse Recovery Charge	Q_{rr}			253		nC

⁵Pulse test : Pulse Width $\leq 300 \mu\text{sec}$, Duty Cycle $\leq 2\%$.⁶Independent of operating temperature.

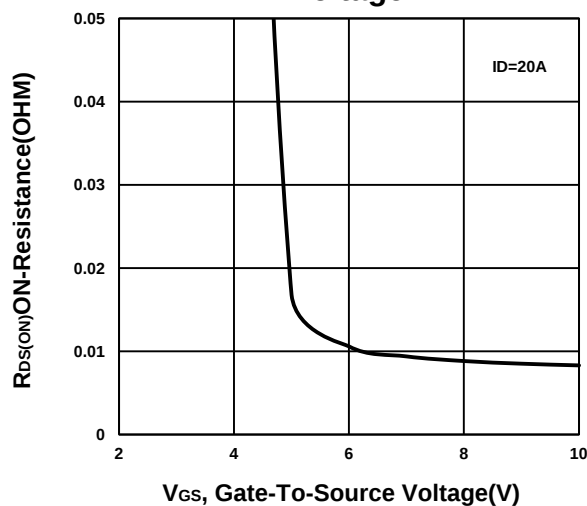
Output Characteristics



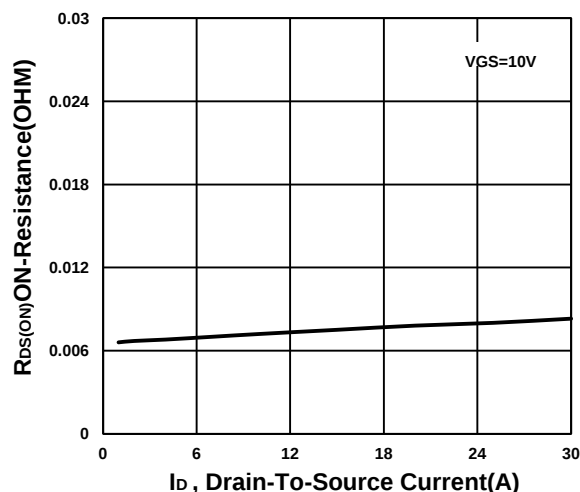
Transfer Characteristics



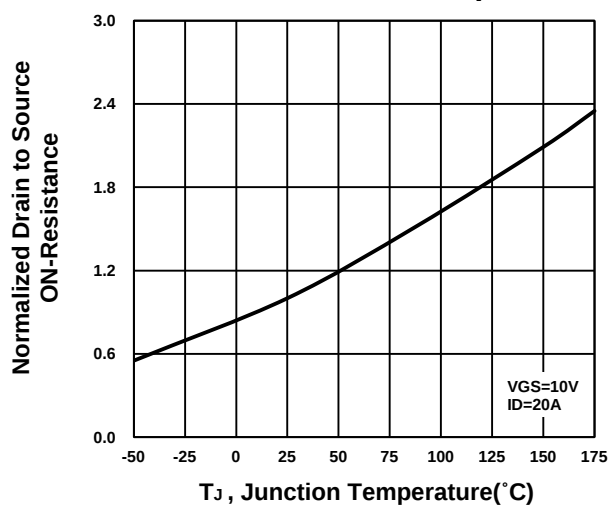
On-Resistance VS Gate-To-Source Voltage



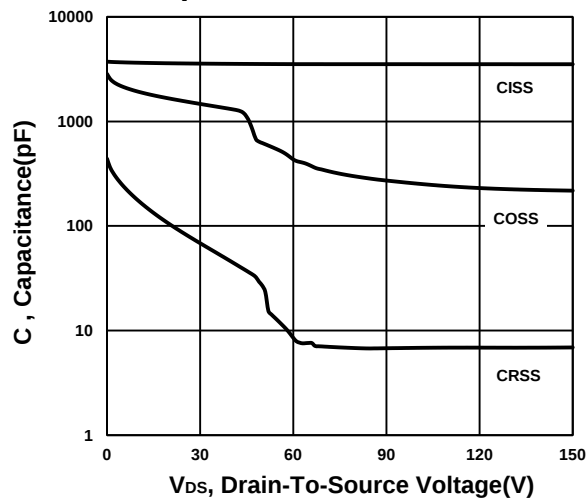
On-Resistance VS Drain Current



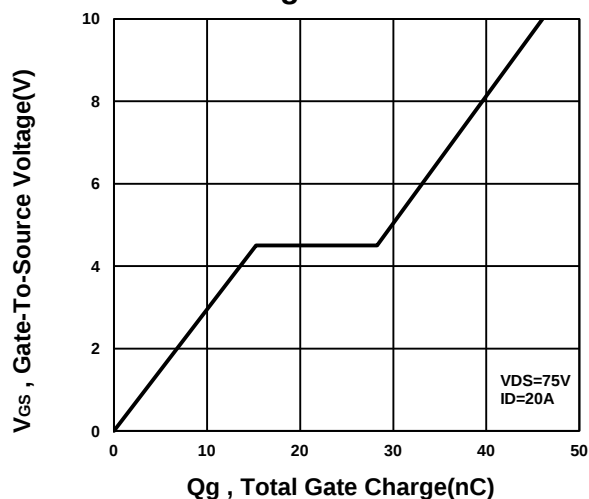
On-Resistance VS Temperature



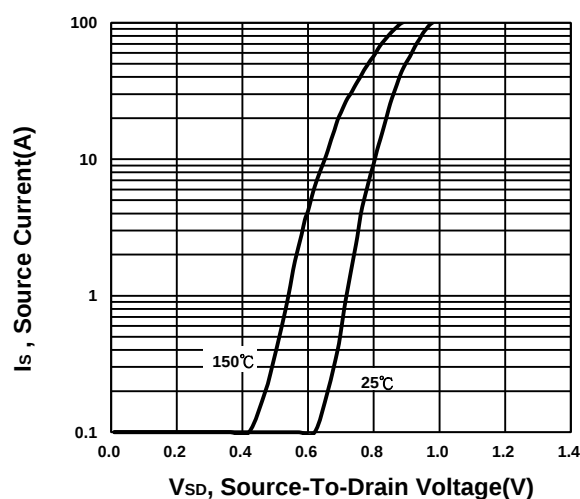
Capacitance Characteristic



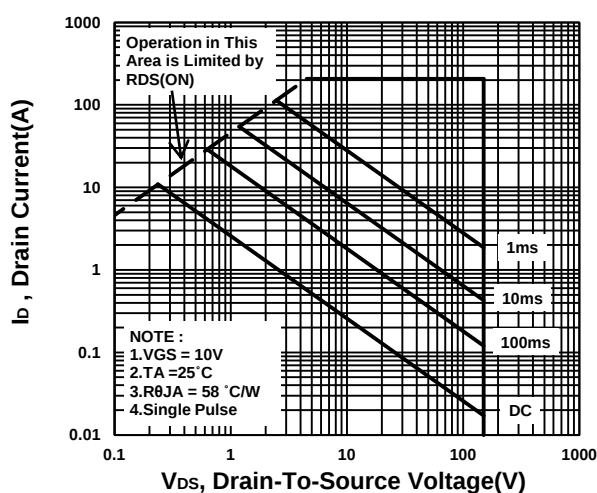
Gate charge Characteristics



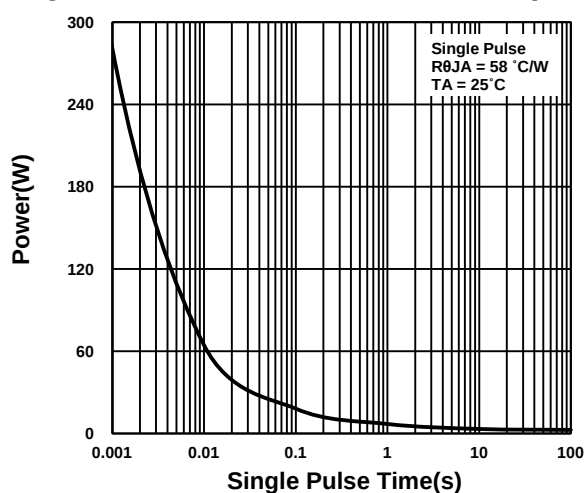
Source-Drain Diode Forward Voltage



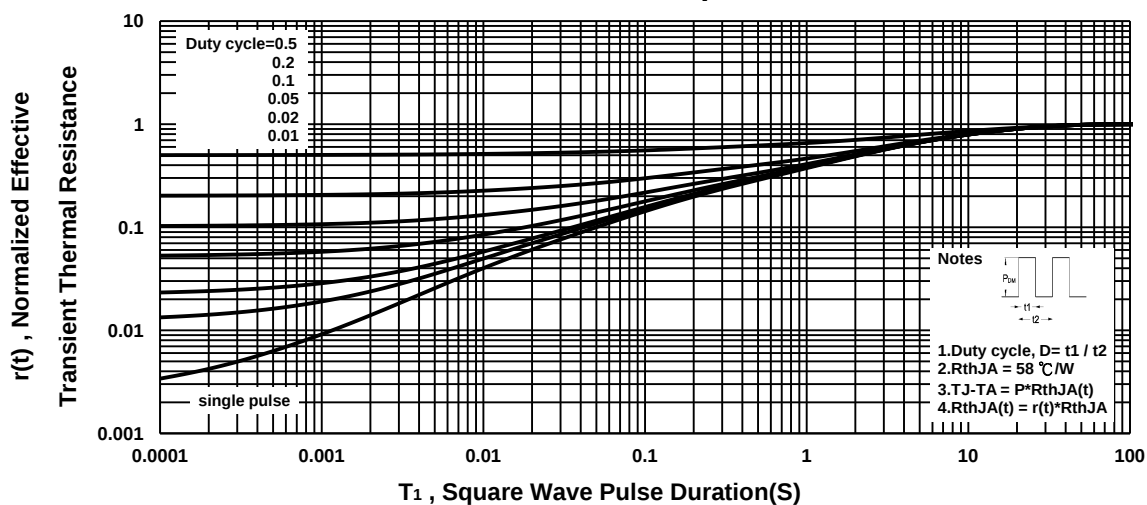
Safe Operating Area



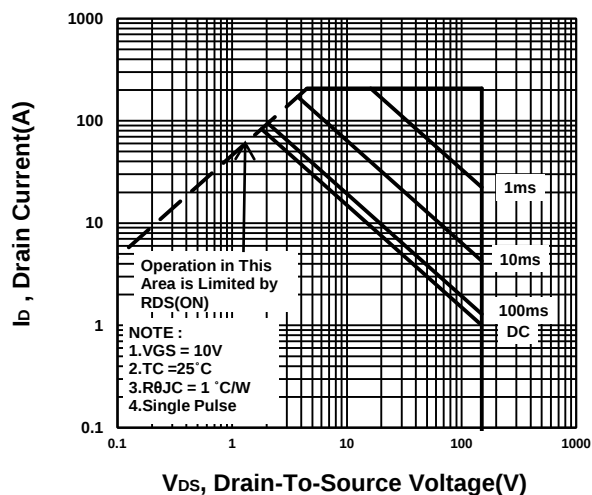
Single Pulse Maximum Power Dissipation



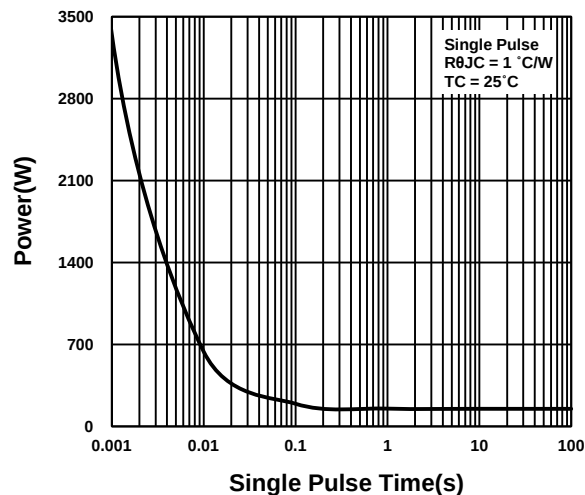
Transient Thermal Response Curve



Safe Operating Area



Single Pulse Maximum Power Dissipation



Transient Thermal Response Curve

